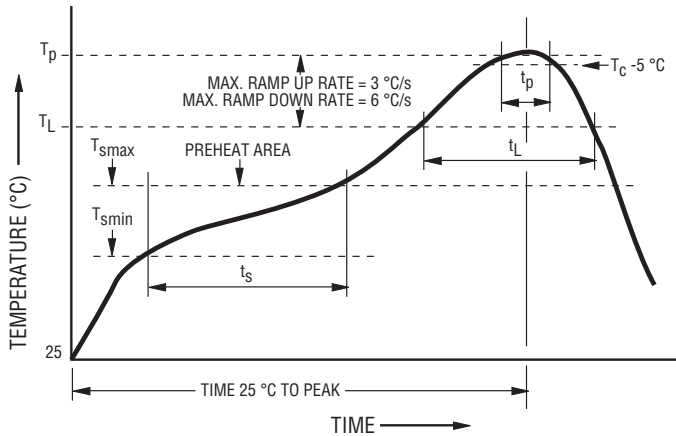


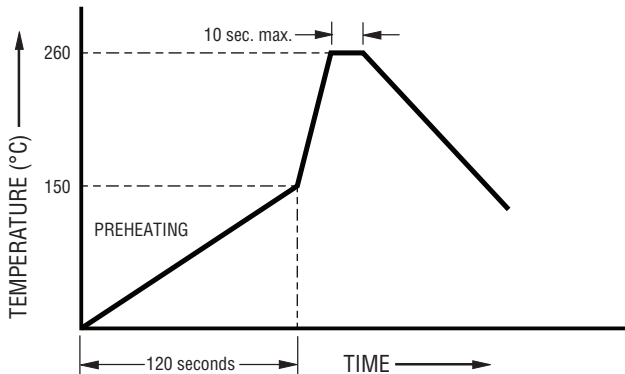
Solder Reflow Recommendations



| Profile Feature | Pb-Free Assembly |
|---|------------------------------------|
| Preheat / Soak: Temperature Min. (T_{smin}) Temperature Max. (T_{smax}) Time (t_s) from (T_{smin} to T_{smax}) | 150 °C 200 °C 60~120 seconds |
| Ramp Up Rate (T_l to T_d) | 3 °C / second max. |
| Liquidous Temperature (T_l) Time (t_L) maintained above T_l | 217 °C 60~150 seconds |
| Peak Package Body Temperature (T_d) | 260 °C |
| Time (t_p)* within 5 °C of the specified classification temperature (T_c) | 30 seconds* |
| Ramp Down Rate (T_d to T_l) | 6 °C / second max. |
| Time 25 °C to Peak Temperature | 8 minutes max. |

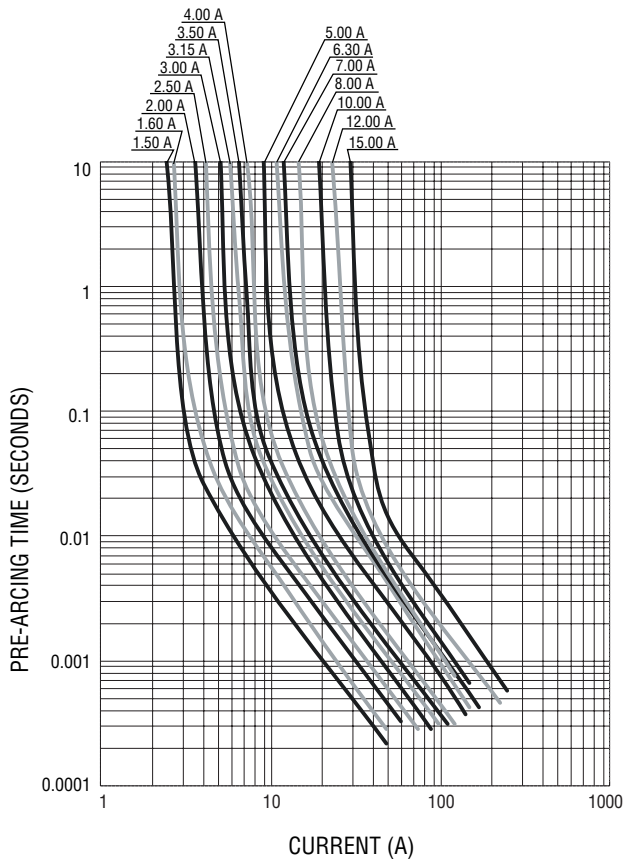
* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

Recommended Temperature Profile for Wave Soldering

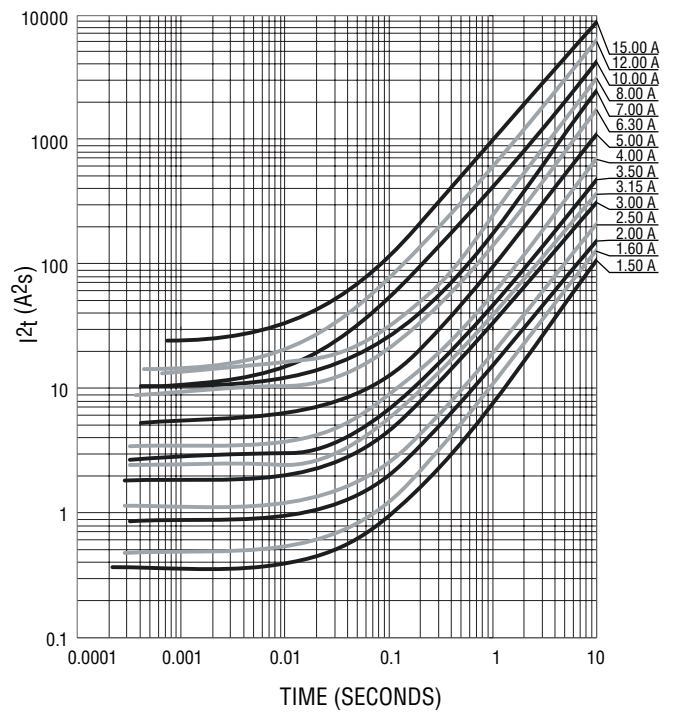


Wave soldering is suitable for 1206 size models.

Average Pre-Arcing Time vs. Current Curves



Average I²t vs. t Curves



BOURNS®

Asia-Pacific: Tel: +886-2 2562-4117 • Email: asiacus@bourns.com

EMEA: Tel: +36 88 520 390 • Email: eurocus@bourns.com

The Americas: Tel: +1-951 781-5500 • Email: americus@bourns.com

www.bourns.com